

# FS20VS-5A

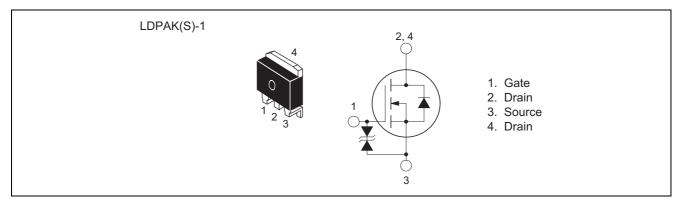
High-Speed Switching Use Nch Power MOS FET

REJ03G0266-0100 Under development Rev.1.00 Aug.20.2004

### Features

- Drive voltage : 10 V
- V<sub>DSS</sub> : 250 V
- $r_{\text{DS(ON)}(\text{max})}$ : 0.19  $\Omega$
- $I_D: 20 A$

### Outline



### Applications

PDP, lamp ballast, SMPS

### **Maximum Ratings**

 $(Tc = 25^{\circ}C)$ 

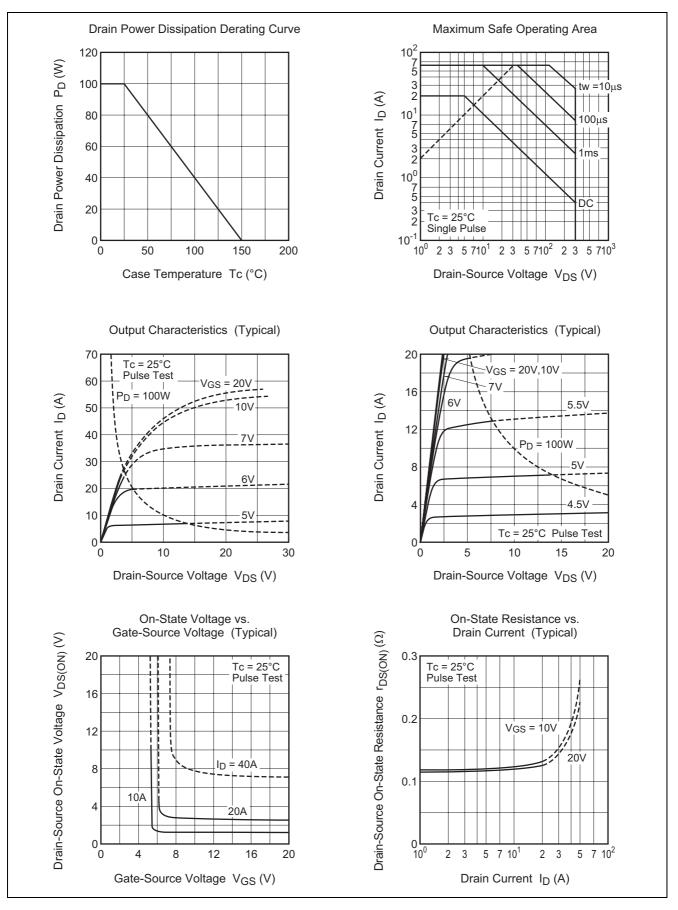
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V <sub>DSS</sub>	250	V	$V_{GS} = 0 V$
Gate-source voltage	V <sub>GSS</sub>	±30	V	$V_{DS} = 0 V$
Drain current	ID	20	Α	
Drain current (Pulsed)	I <sub>DM</sub>	60	Α	
Avalanche current	I <sub>DA</sub>	20	Α	L = 200 μH
Maximum power dissipation	PD	100	W	
Channel temperature	Tch	- 55 to +150	°C	
Storage temperature	Tstg	- 55 to +150	°C	
Mass	—	1.2	g	Typical value

## **Electrical Characteristics**

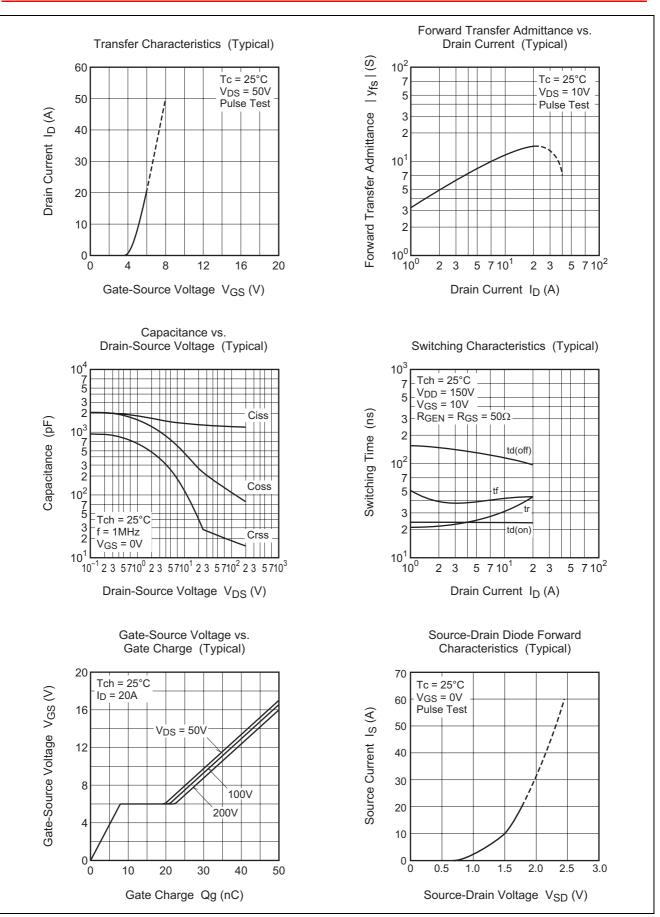
(101 - 25 C)	(Tch	$= 25^{\circ}C)$
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Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	250			V	$I_{D} = 1 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate-source breakdown voltage	V <sub>(BR)GSS</sub>	±30	_	_	V	$I_G = \pm 100 \ \mu A$ , $V_{DS} = 0 \ V$
Gate-source leakage current	I <sub>GSS</sub>	_		±10	μΑ	$V_{GS}$ = ±25 V, $V_{DS}$ = 0 V
Drain-source leakage current	I <sub>DSS</sub>	_		1	mA	$V_{DS} = 250 \text{ V}, V_{GS} = 0 \text{ V}$
Gate-source threshold voltage	V <sub>GS(th)</sub>	2.5	3.0	3.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Drain-source on-state resistance	r <sub>DS(ON)</sub>	_	0.15	0.19	Ω	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}$
Drain-source on-state voltage	V <sub>DS(ON)</sub>	_	1.5	1.9	V	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}$
Forward transfer admittance	y <sub>fs</sub>	8.5	12		S	$I_D = 10 \text{ A}, V_{DS} = 10 \text{ V}$
Input capacitance	Ciss	_	1300		pF	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$
Output capacitance	Coss	_	200		pF	f = 1MHz
Reverse transfer capacitance	Crss	_	30		pF	
Turn-on delay time	t <sub>d(on)</sub>	_	22		ns	$V_{DD} = 150 \text{ V}, I_D = 10 \text{ A},$
Rise time	tr	_	35		ns	V <sub>GS</sub> = 10 V,
Turn-off delay time	t <sub>d(off)</sub>	_	120		ns	$R_{GEN} = R_{GS} = 50 \ \Omega$
Fall time	t <sub>f</sub>	_	45		ns	
Source-drain voltage	V <sub>SD</sub>	_	1.5	2.0	V	$I_{S} = 10 \text{ A}, V_{GS} = 0 \text{ V}$
Thermal resistance	Rth(ch-c)	_	—	1.25	°C/W	Channel to case

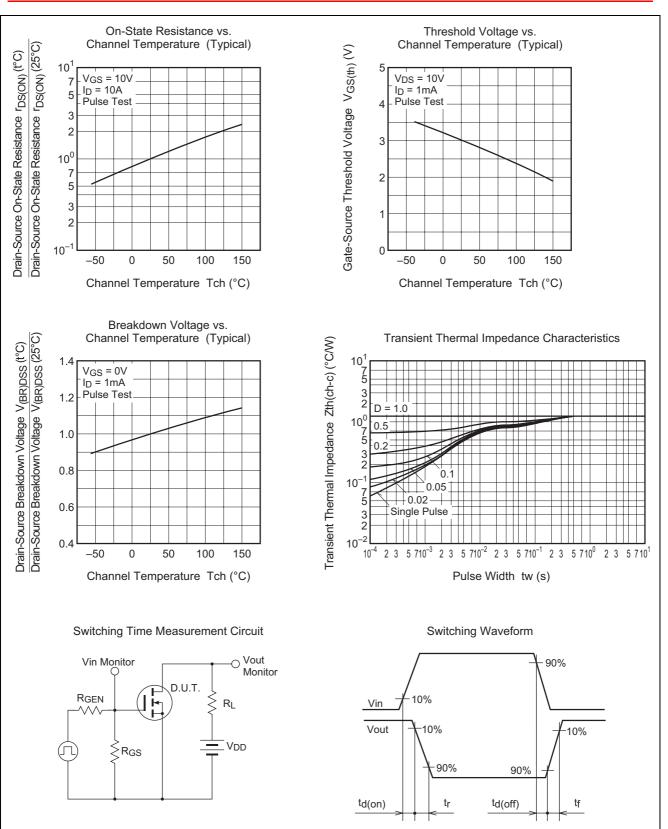
### **Performance Curves**





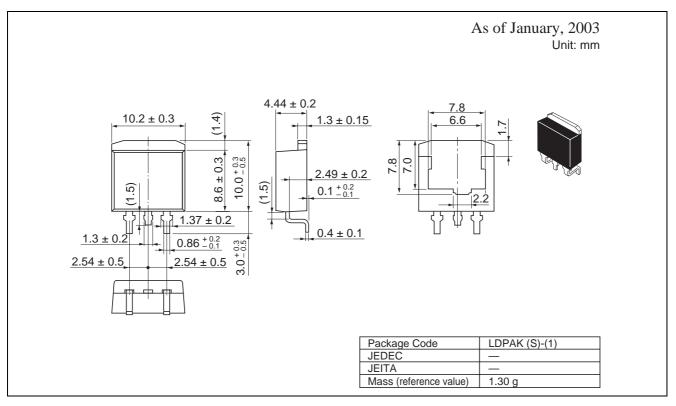






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### **Package Dimensions**



### Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example			
Surface-mounted type	Taping	1000	Type name – T +Direction (1 or 2) +1	FS20VS-5A-T11			

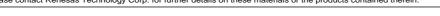
Note : Please confirm the specification about the shipping in detail.

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